Icemos Technology Ltd Product Specification 1000.709501 Issue Date 20 January 2022 09:2

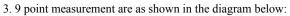
Part Number (7
Part Number (Customer

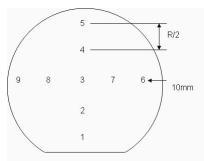
Category	Parameter		Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110} +/- 1 degree	Customer supplied material
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Customer supplied material
	4.0	Secondary Flat Orientation	none or SEMI Standard	Customer supplied material
	5.0	Overall Thickness	409.00 +/- 12.00 μm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<5.00μm	Guaranteed by Process
	7.0	Bow	<60.00μm	ADE to ASTM F534, 100%
	8.0	Warp	<60.00μm	ADE to ASTM F534, 100%
	9.0	Edge Chips	0	Bright Light, 100%
	10.0	Edge Exclusion	5mm	
HandleSilicon	11.0	Handle Growth Method	FZ	Customer supplied material
	12.0	Handle Orientation	{100} +/- 0.5 degree	Customer supplied material
	13.0	Handle Thickness	400.00 +/- 10.00 μm	ADE, 100%
	14.0	Handle Doping Type	Undoped	Customer supplied material
	15.0	Handle Dopant	Undoped	Customer supplied material
	16.0	Handle Resistivity	>10,000 Ohm-cm	Customer supplied material
	17.0	Backside Finish	Polished with oxide and lasermark	Guaranteed by process
BuriedOxide	18.0	Oxide Type	Thermal	
	19.0	Oxide Thickness	10,000.00 +/- 500.00 A	Nanospec centre point, 4%
	20.0	Oxide formed on	Handle	
DeviceSilicon	21.0	Device Growth Method	FZ	Customer supplied material
	22.0	Device Orientation	{100} +/- 0.5 degree	Customer supplied material
	23.0	Nominal Thickness	8.00 +/- 1.00 μm	Filmetrics 9pts, 100% (note3)
	24.0	Distance to device silicon edge from wafer edge	Typical by Process	
	25.0	Device Doping Type	Undoped	Customer supplied material
	26.0	Device Dopant	Undoped	Customer supplied material
	27.0	Device Resistivity	>10,000 Ohm-cm	Customer supplied material
	28.0	Surface Voids	None	Bright Light, 100% (note2)
	29.0	Haze	None	Bright Light, 100% (note2)
	30.0	Scratches	none on the front-side	Bright Light, 100% (note2)

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Part Number		Customer	
Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging:	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspec	ction performed using microscope scan as below. 5x objective.	
	2. All bright light ins	pections performed exclude all wafer area outside the edge exclusion	on defined in Overall

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.





Additional Information